DAMIC-M activities at LSM in 2022 and 2023 **Dark Matter In CCDs at Modane**

DAMIC-M detector

Activities in 2022

- Low Background Chamber (LBC),
- First science results.

Plans and requirements for 2023

R. Smida for the DAMIC-M Collaboration











DAMIC-M at LSM

Goal: Detect nuclear and electron recoils to search for light dark matter candidates (eV to GeV).

Detector with ~200 CCDs

- CCDs made from high resistivity, n-type, high purity Si,
- 9M pixels, 670 µm thickness, ~3.5 g mass,
- single-electron resolution CCDs, called skipper CCDs,
- the energy threshold of 2-3 electrons (~10 eV),
- the total exposure of 1 kg-year.

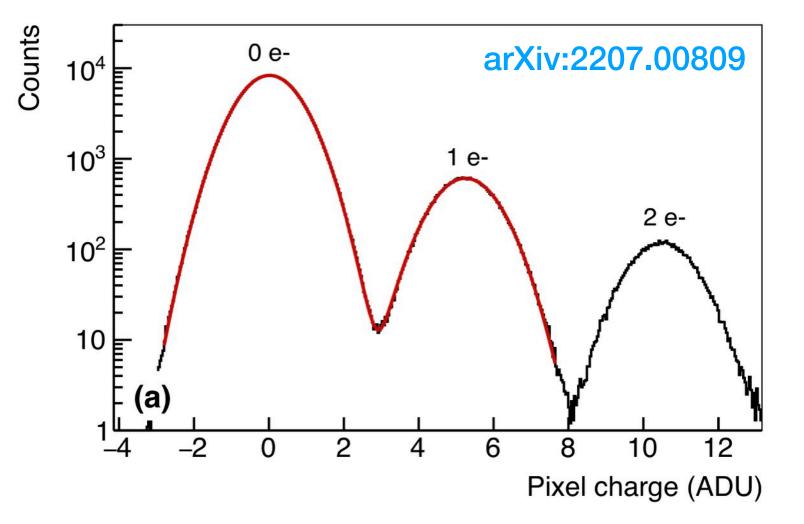
Low background rate of $\mathcal{O}(0.1)$ dru

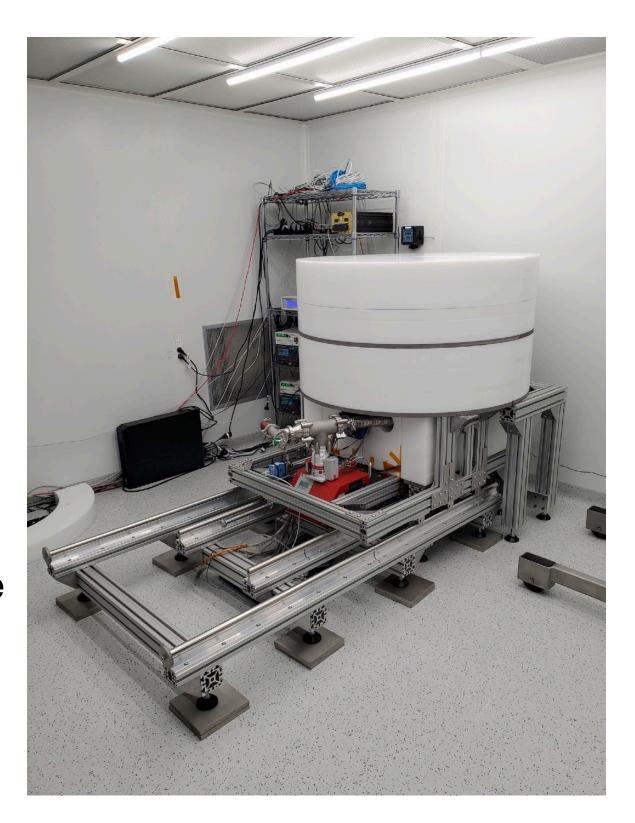
- Clean materials (Si, electro-formed copper (EFC), ancient Pb),
- mitigate the cosmogenic activation and surface deposition (Rn or dust),
- use pixelization for background rejection.

Low Background Chamber (LBC) in the DAMIC-M detector cleanroom at LSM (26.7 m², ISO 5, Rn (7±1) Bq/m³)









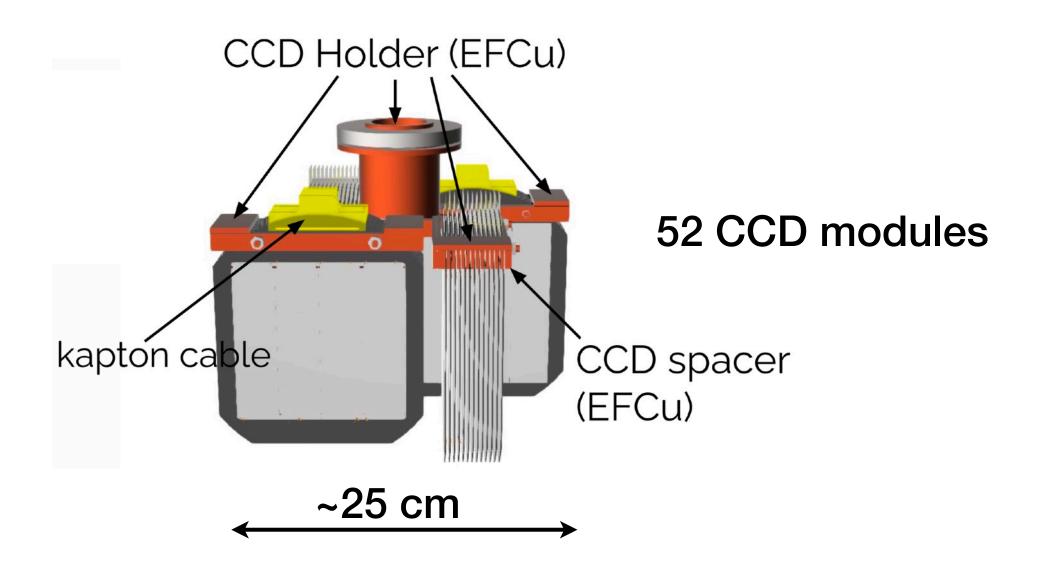
Detector design

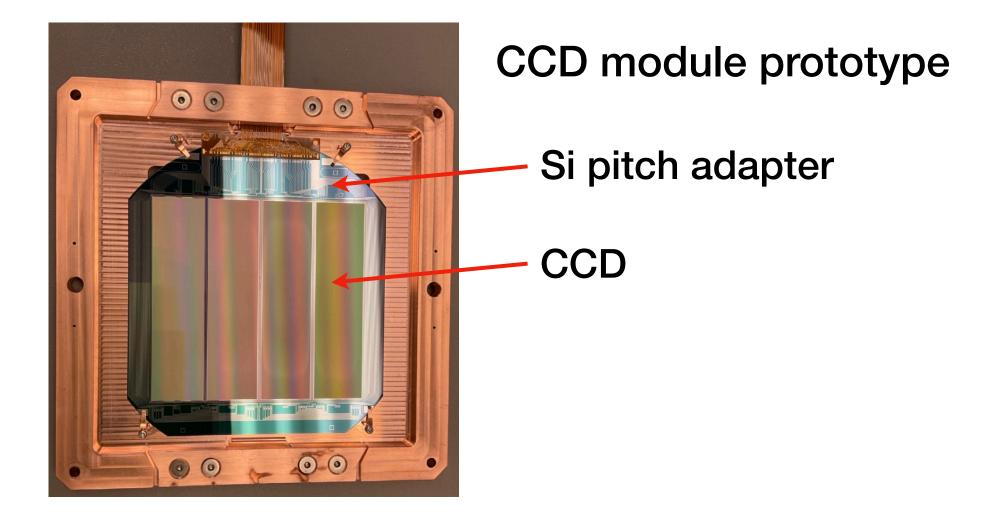
A compact array of 52 CCD modules, i.e. a Si pitch adapter frame with four skipper CCDs.

We will use science-grade CCDs carefully selected from ~750 devices. All devices will be packaged and tested in a dedicated cleanroom (ISO5, ~30 m²) at LSM. They must be kept in clean environment, flushed with either N₂ or Rn-free air, and controlled humidity (50±10)%.

Voltages and signals will be carried by specially developed low-background flex cables of ~1.5 m length.

Two CCD module prototypes will be characterized in LBC at LSM during next months.





Detector design

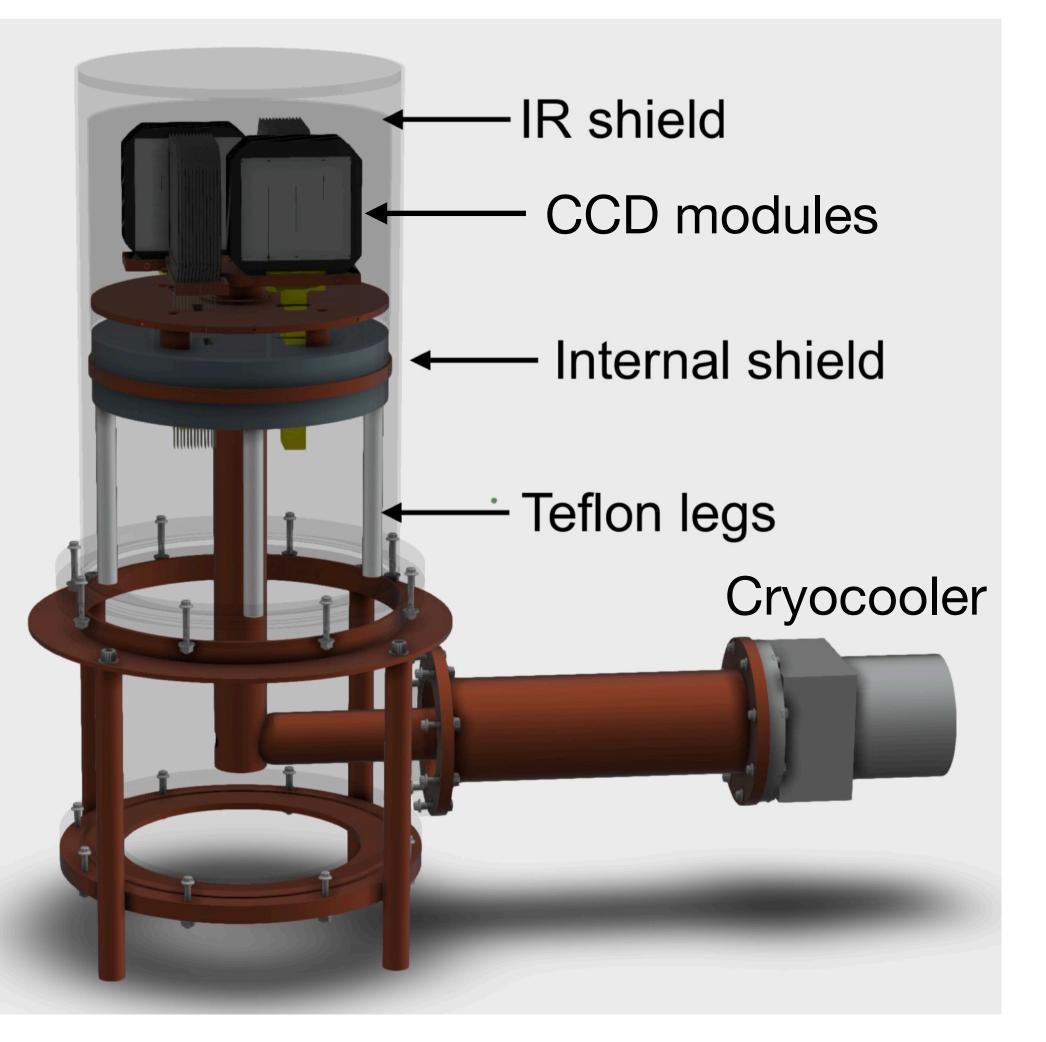
CCD modules are connected to a cold copper hanger and encapsulated in an IR shield. Flex cables bring voltages and signals to a feedthrough flange (not shown).

Parts above the internal shield and the cryostat, are from copper electro-formed and machined at LSC. Other cryostat parts are from OFHC copper.

Ancient Pb plate inside and 5 cm cylinder around the cryostat. In this configuration, we require ~700 kg of ancient Pb.

Cooling with a cryocooler ($T_{CCD} \sim 125$ K) and will not need to have a supply of LN₂.

 \bullet



External shield (Pb, HDPE) and support structure, • Custom electronics for fast readout and low noise, • DAQ system (PCs, remote connection, etc.).

Background

Getting close to 0.1 dru level.

Guided by results of DAMIC at SNOLAB (arXiv: 2110.13133) and extensive Geant4 simulations.

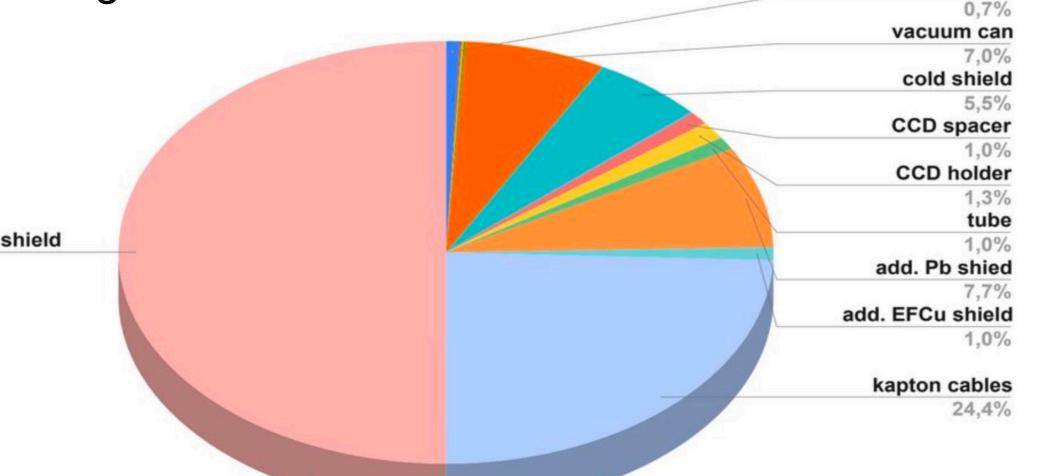
external Pb shield 50,0%

Efforts dedicated to

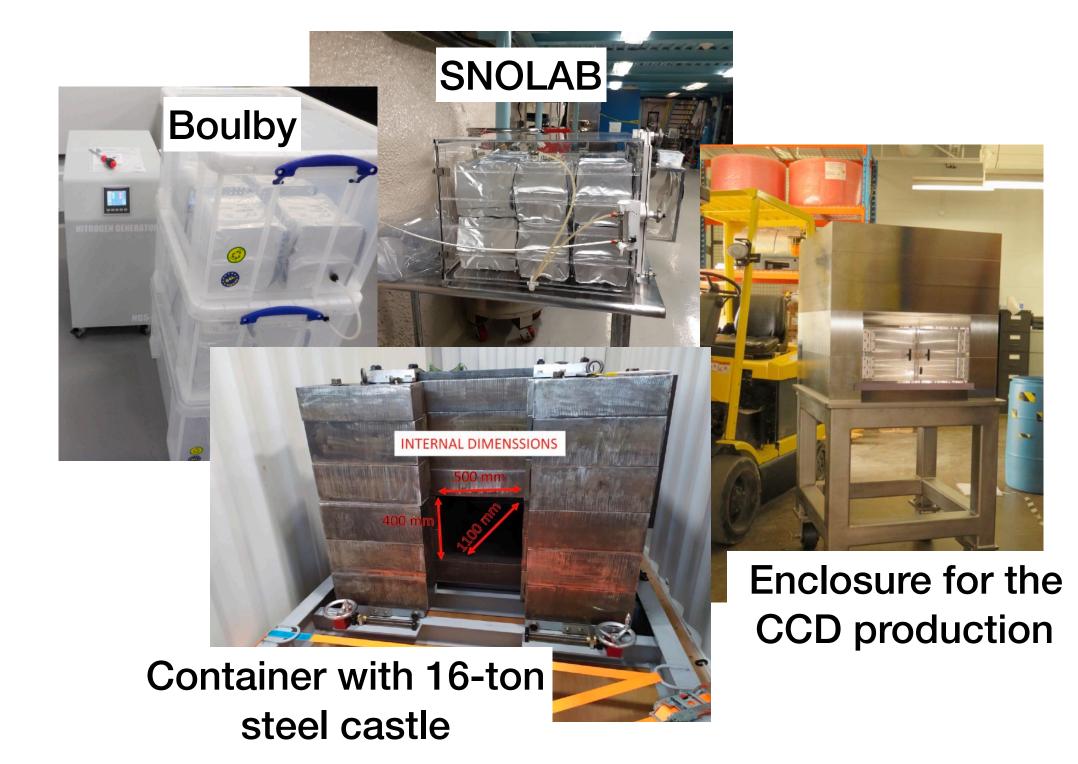
- Minimize the cosmogenic activation of Si and Cu (shielding, underground storage, expedite processing, etc.). Critical is to package and test CCDs at LSM.
- Limit the exposure of CCDs to the air and dust.
- Only electro-formed copper parts close to CCDs.
- Newly developed clean CCD flex (kapton) cables.
- Sufficient thickness of ancient lead. Precise measurement of ²¹⁰Pb in the bulk of LSM ancient lead is missing.
- Assay of all materials.
- Proper cleaning procedures.

Some of the above was already implemented for LBC.

Background contributors

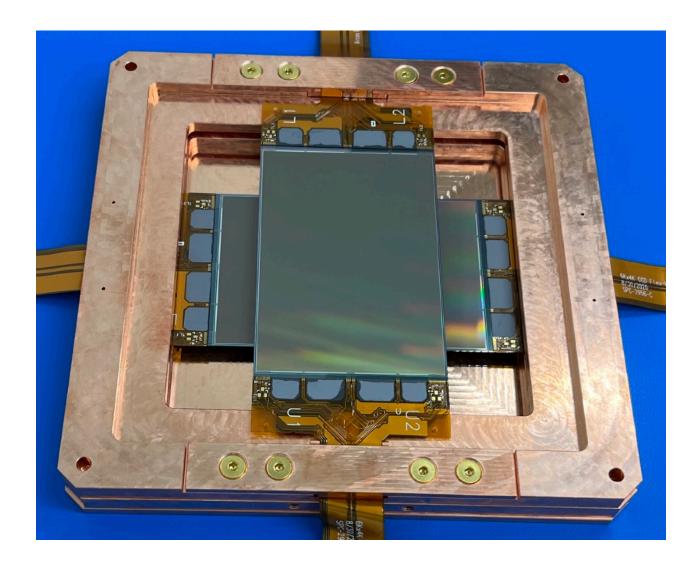


cryo



A prototype detector at LSM with four objectives, built in the winter 2021 and successfully running since Feb 2022. Two upgrades in 2022 and one more starting next week (Jan 30 - Feb 17, 2023).

1. Characterize DAMIC-M components in a low background environment (CCD dark current, noise level, radioactive background of materials, etc.), (



- Two skipper CCDs, each with 24M pixels and mass 9.1 g,
- no material between CCDs,
- two-layer flex cable.



- EFC lids from LSC,
- inner 2 cm LSM ancient lead, then TFA lead.



- Outer shielding (Pb and HDPE),
- support structure,
- slow control,
- electronics.

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- Gain working experience at LSM, 2.



Continuous support by LSM and LPSC, and also other experiments, is highly appreciated!

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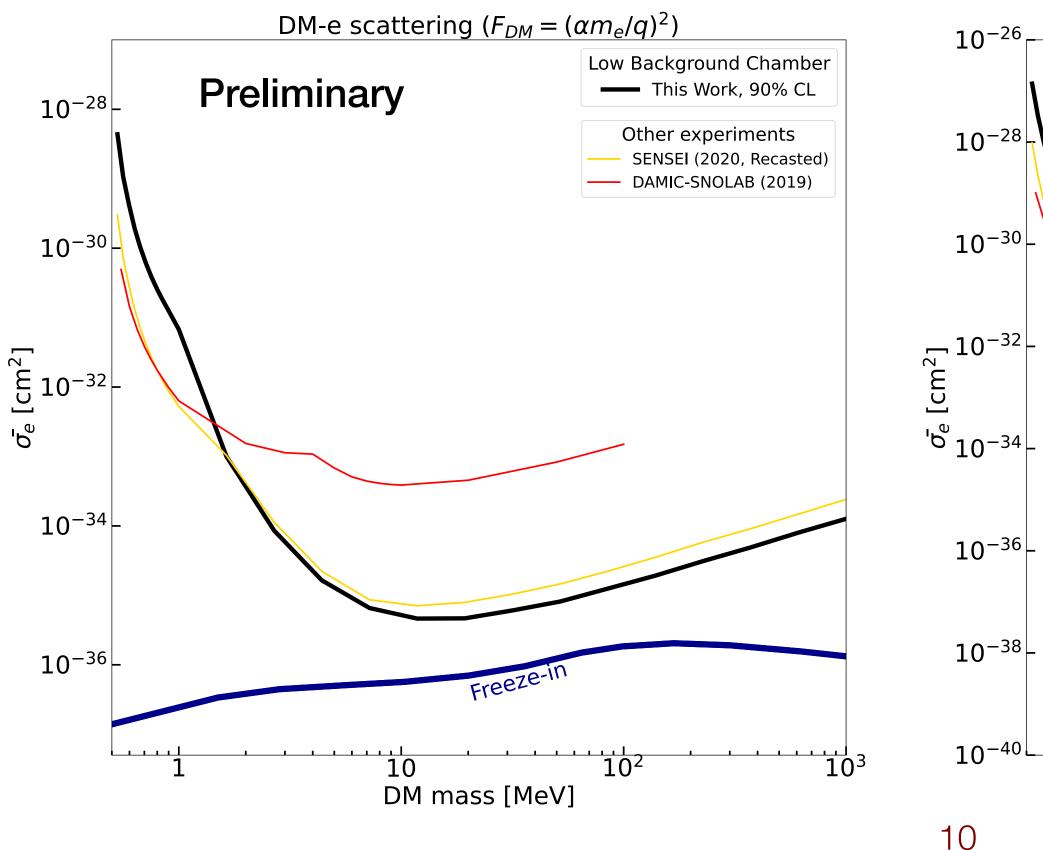
Last db update: Jan 25, 2023 @ 16:16:21. Sensors values in yellow are more than 10 minutes old. 2nd system Amplifer+ board (2nd_Current_1) Current on 2nd system Amplifer- board (2nd_Current_2) 0,0227 0,0226 (A) (A) no 2nd system Leach board (2nd_Current_3) Voltage on 2nd system Amplifer+ board (2nd_Voltage_1) 0,0355 5.0000 (A) (V) 2nd system Amplifier- board (2nd_Voltage_2) Voltage on 2nd system Leach board (2nd_Voltage_3) 5.0002 (V) (V) (V) WC controller of CryoTelGT (Power_Output_AVC) Reject temperature of CryoTelGT (Reject_Temp) 190.0000 (C) (W) (C) ure of CryoTelGT cold head (Temp_Cooler) Heater power output percentage (sensor) (Heater_100W) 866,2220 (%) (units) (%)	<u>Plots MPlot Scatter Sys Log Runs Users Alarms Config</u>	g <u>Control LogBook</u> <u>Cams</u> You are logged in as smida from 127.0.0.1.
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(K/min) (K)	0.100	115.000
	(K/min)	(K)

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- 2. Gain working experience at LSM,
- 3. Test of other fundamental DAMIC-M components (e.g. Front End electronics, slow control, DAQ software, data transfer and data quality monitoring, remote control), (
- 4. Science results with this small detector.

107 Best Fit CCD 6415-La 1e events 10⁶ 2e events 3e events 10⁵ Data CCD 6415-La Number of entries 104 preliminary 10³ 10² 10¹ 10⁰ 10^{-1} -2 -1 1 0 2 3 Number of Electrons DM-e scattering ($F_{DM} = (\alpha m_e/q)^2$) DM-e scattering ($F_{DM} = 1$) 10^{-26} Low Background Chamber Low Background Chamber Preliminary Preliminary This Work, 90% CL — This Work, 90% CL 10-28 10-28 Other experiments Other experiments SENSEI (2020, Recasted) SENSEI (2020, Recasted) DAMIC-SNOLAB (2019) DAMIC-SNOLAB (2019) PandaX-II (2021) 10^{-30} XENON-1T (2019) 10^{-30} ⁻²⁻³² ⁻^θ 10⁻³⁴ 10^{-34} 10^{-36} 10^{-38} Freeze-Out 10-36 Freeze-II 10-40 10^{3} 10³ 10^{2} 10^{2} 10 10 DM mass [MeV] DM mass [MeV]

First science results The analysis of the pixel-charge distribution (right figure) measured by LBC gives the world-leading limits on DM-electron scattering (figures below). Preliminary results have been presented at conferences, arXiv:2210.12070. A journal Letter paper reporting an improved limit is written and under the Collaboration review. Other analysis are ongoing. [2 0 -32 م'



DAMIC-M at LSM in 2023

- Background data with LBC. Q4 2022 CCD pre-processing phase has started.
- Q1 2023 Start taking data with the new CCD modules. The CCD production phase. Finalize the detector design. Start electro-forming copper at LSC.
- Q2 2023 Shipment of CCDs to LSM. Clean and Rn-free storage space for CCDs. Production of Si pitch adapters. Ideally, in a fab in or close to Grenoble. Delivery of instruments (cold probing setup, wire bonder, two test chambers).
- Q3-Q4 2023 Cold probing and packaging of CCDs at LSM. grade detectors (defects, amplifiers, dark current, single electron resolution).

Our goal is to complete installation in Q3 2024 and start data taking by the end of 2024. One year minimum of science data taking.

Work on LBC (Jan 30 - Feb 17), installation of open-shield mechanism and CCD modules.

A cleanroom for probing, packaging and testing CCDs (~30 m², ISO 5, humidity 40-60%).

Tests of CCD modules, some of them with radioactive source(s). Select the best science-

Disassemble/relocate LBC start preparing this cleanroom for the full-scale DAMIC-M detector.

Required infrastructure/support from LSM

- 1. A dedicated cleanroom (ISO5, \sim 30 m², humidity (50±10)%) for packaging and testing CCDs at LSM.
- 2. Supply of Rn-free air and N₂.
- 3. Clean and Rn-free storage cabinets for Si and Cu parts.
- 4. Ancient lead (~700 kg). Precise measurement of ²¹⁰Pb in LSM ancient lead is still missing.
- 5. Radioactive sources for CCD tests. (If feasible, we will be interested in using activated source(s) for photo-neutron measurement.)
- Support with shipments, construction and chemical cleaning. 6.

For a successful completion of the DAMIC-M program is essential that adequate space and infrastructure is allocated to the experiment in 2023 and 2024. The ERC Advanced Grant ends in 2024.